2SJ248

Silicon P-Channel MOS FET

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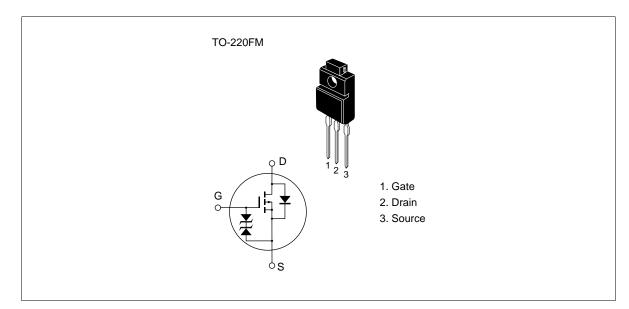
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device can be driven from 5 V source
- Suitable for switching regulator, DC-DC converter

Outline





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Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-100	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	-8	А	
Drain peak current	I _{D(pulse)} *1	-32	А	
Body to drain diode reverse drain current	I _{DR}	-8	А	
Channel dissipation	Pch*2	25	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_c = 25^{\circ}C$

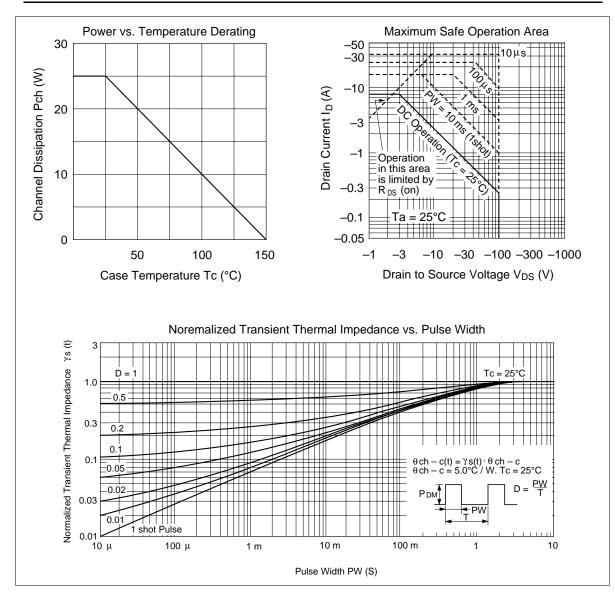
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSS}$	-100	_	_	V	$I_{\rm D} = -10$ mA, $V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}			±10	μΑ	$V_{gs} = \pm 16 \text{ V}, V_{ds} = 0$
Zero gate voltage drain current	I _{DSS}		_	-250	μΑ	$V_{\rm DS} = -80$ V, $V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.0	V	$I_{\rm D} = -1 \text{ mA}, V_{\rm DS} = -10 \text{ V}$
Static drain to source on state	$R_{DS(on)}$		0.25	0.3	Ω	$I_{\rm D} = -4$ A, $V_{\rm GS} = -10$ V ^{*1}
resistance		_	0.3	0.45	Ω	$I_{\rm D} = -4$ A, $V_{\rm GS} = -4$ V ^{*1}
Forward transfer admittance	y _{fs}	3.0	5.5		S	$I_{\rm D} = -4$ A, $V_{\rm DS} = -10$ V ^{*1}
Input capacitance	Ciss		880		pF	$V_{DS} = -10 V, V_{GS} = 0,$
Output capacitance	Coss		325		pF	f = 1 MHz
Reverse transfer capacitance	Crss		80		pF	
Turn-on delay time	t _{d(on)}		12		ns	$I_{D} = -4 \text{ A}, V_{GS} = -10 \text{ V},$
Rise time	t,		47		ns	$R_{L} = 2 \Omega$
Turn-off delay time	t _{d(off)}		150		ns	
Fall time	t _f		75		ns	
Body to drain diode forward voltage	V_{DF}	_	-1.0	_	V	$I_{\rm F} = -8$ A, $V_{\rm GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	170	—	ns	$I_F = -8 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu \text{s}$

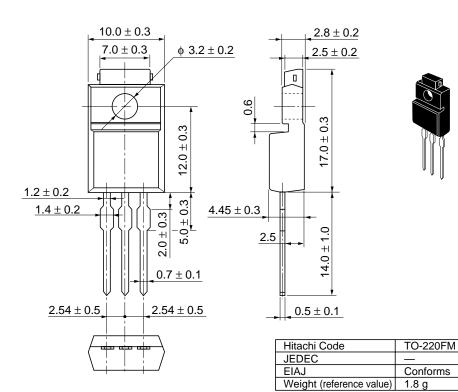
Note: 1. Pulse test

See characteristic curves of 2SJ247

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Unit: mm



Cautions

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